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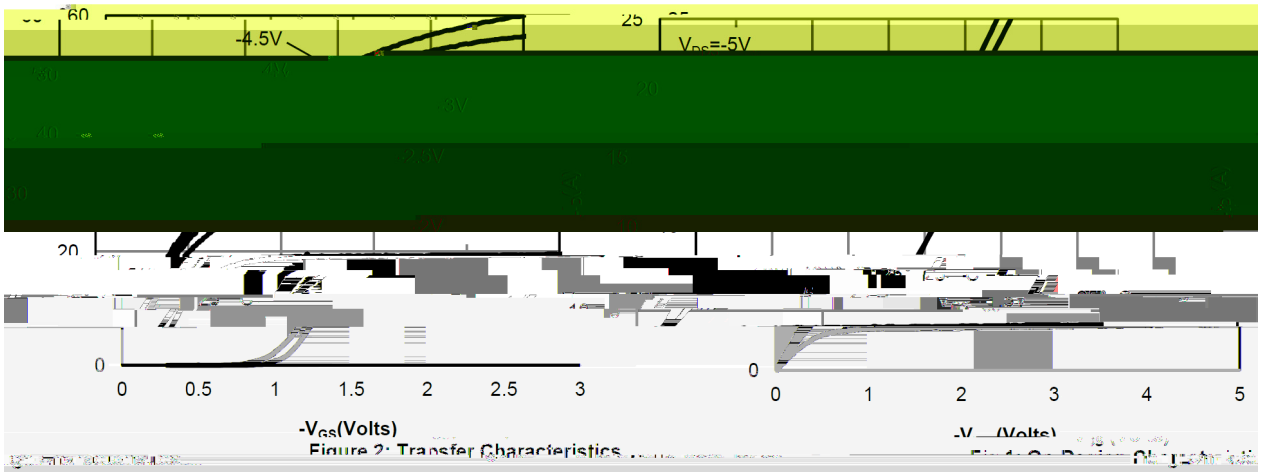
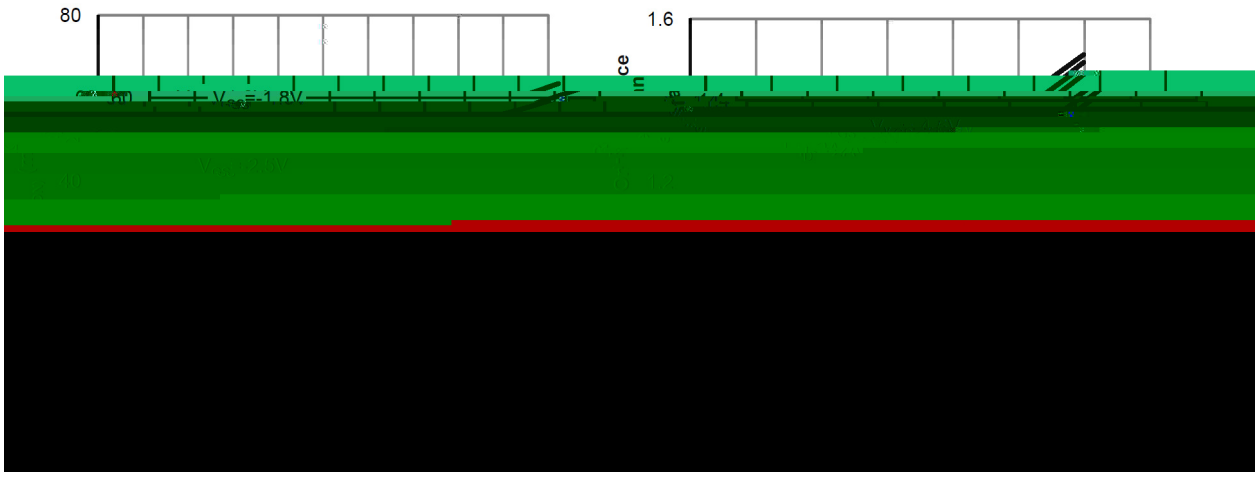
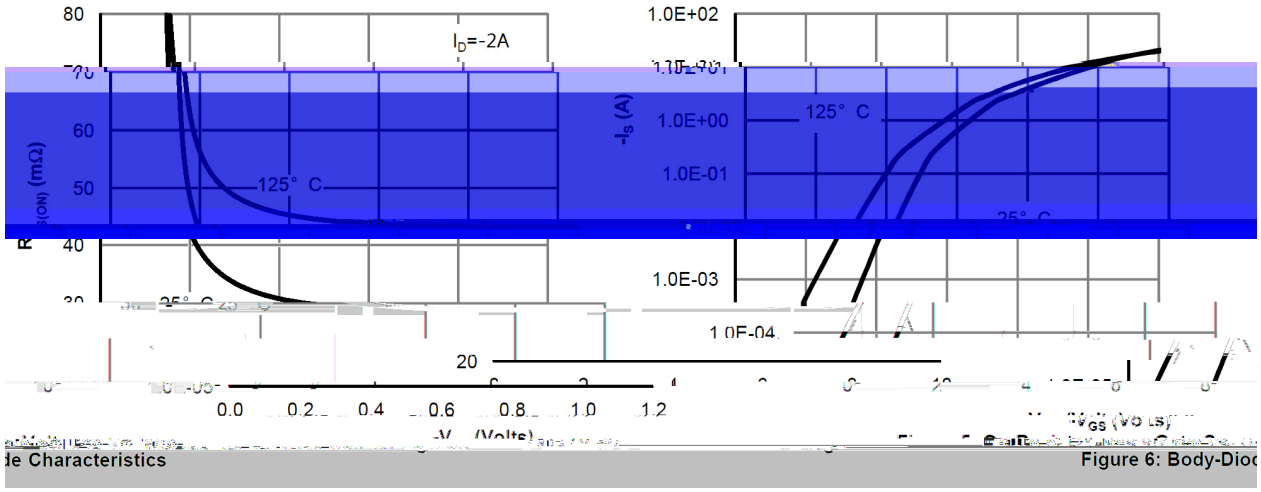


Figure 2: Transfer Characteristics

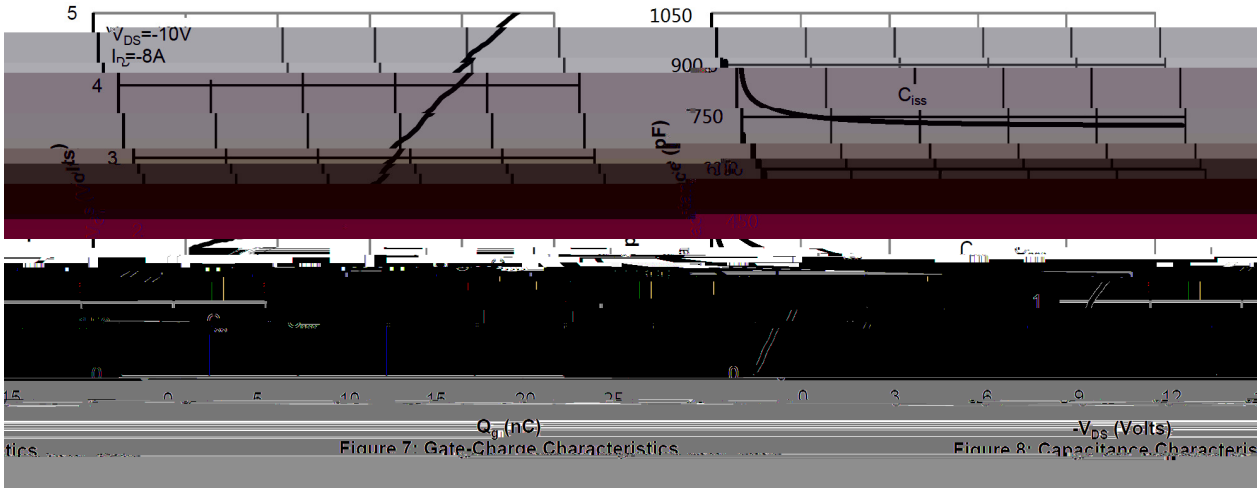




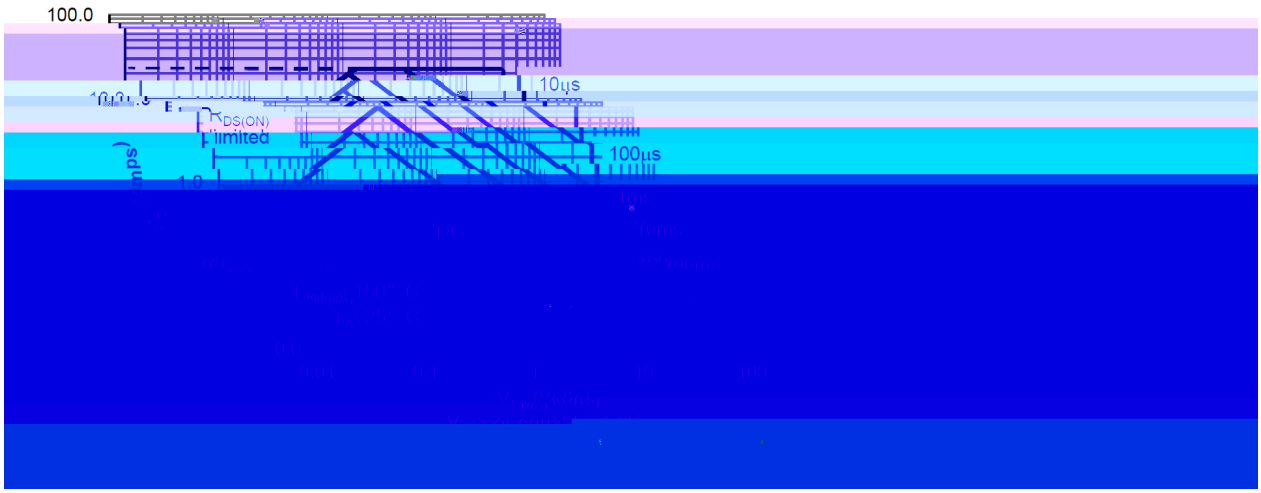
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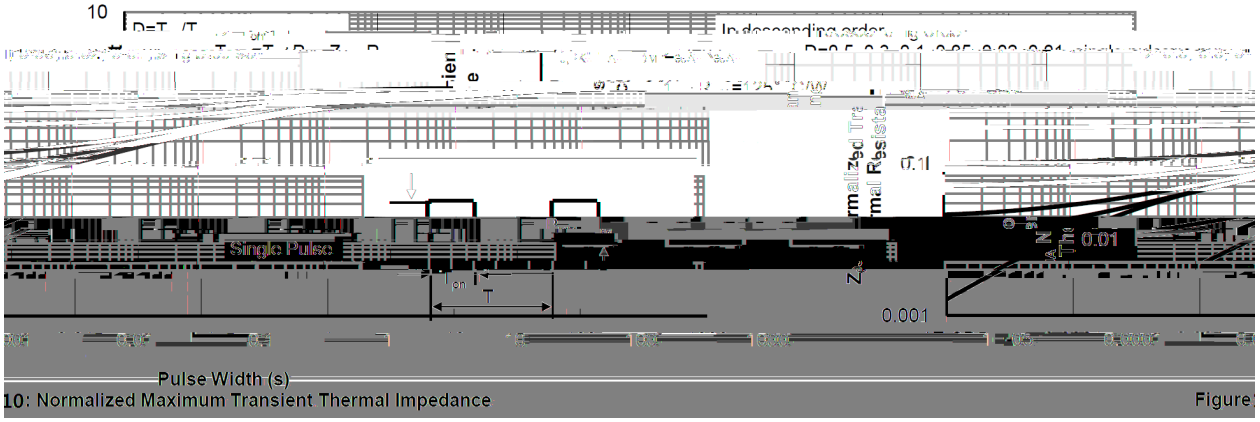
Figure 6: Body-Diod

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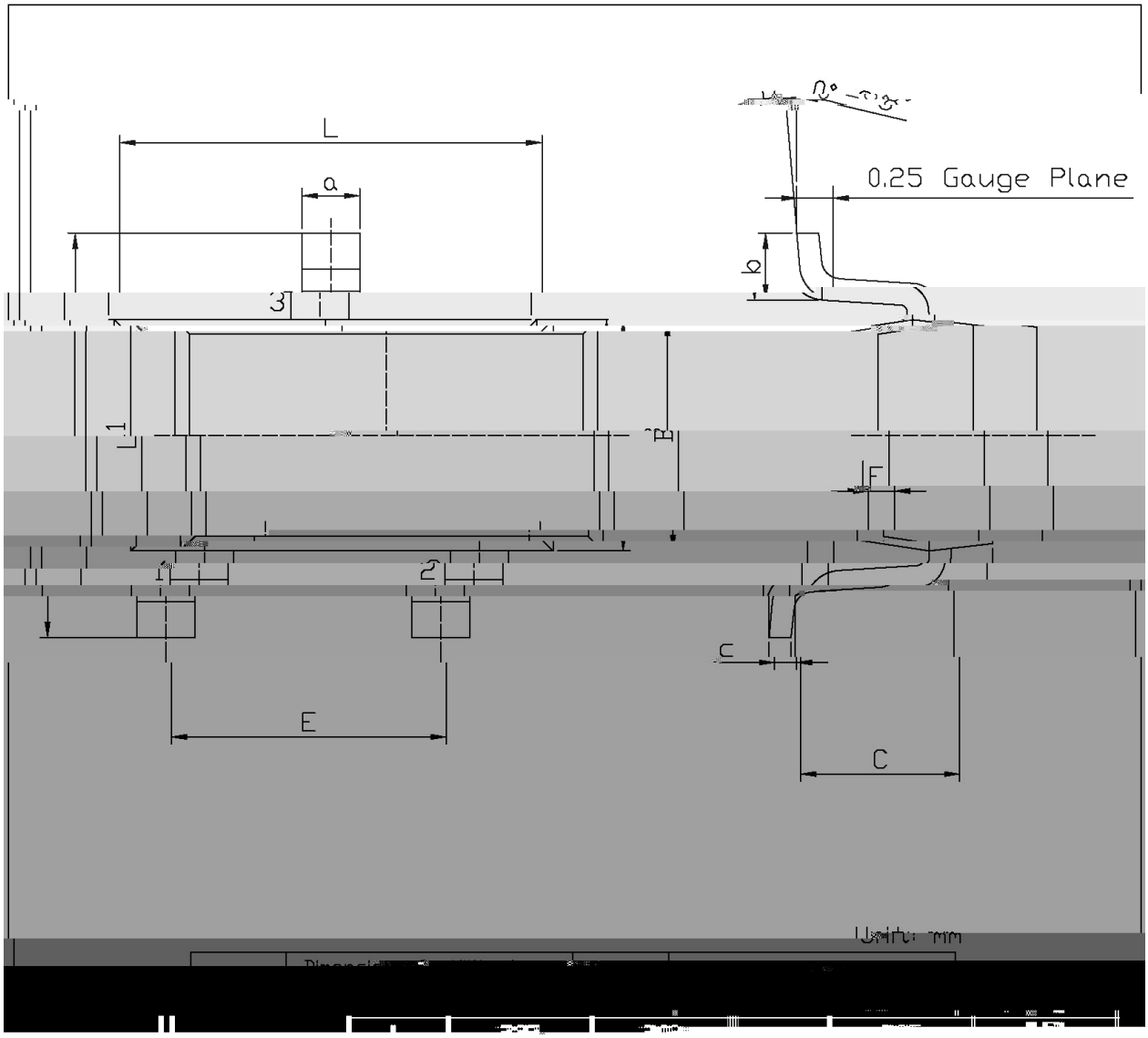


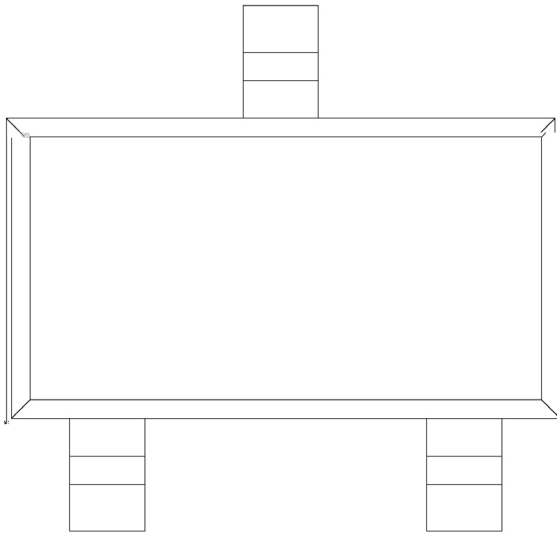
tics Figure 7: Gate-Charge Characteristics Figure 8: Capacitance Characteris



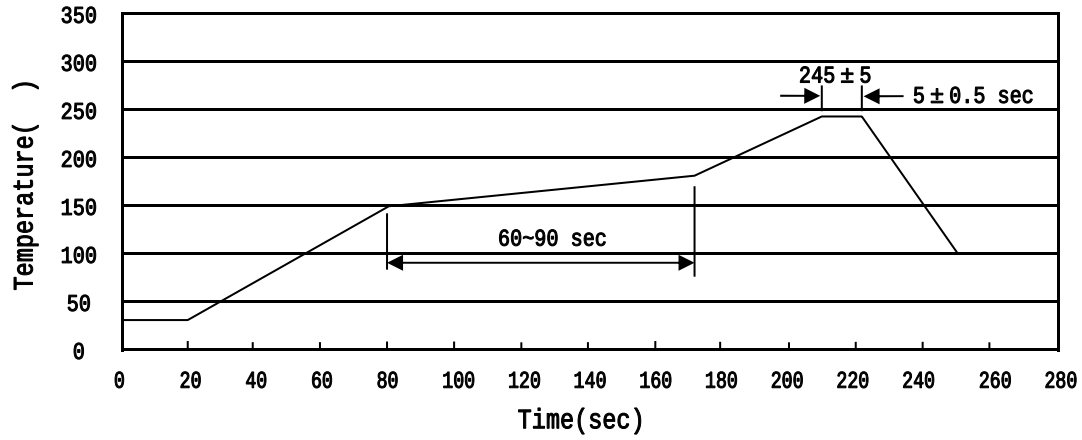


10: Normalized Maximum Transient Thermal Impedance Figure


L
a
3
L1
B
F
b
0.25 Gauge Plane
1
2
E
C
c
Unit: mm



Temperature Profile for IR Reflow Soldering(Pb-Free)



± ± ± ±

± ±

	Units/Reel /	Reels/Inner Box /	Units/Inner Box /	Inner Boxes/Outer Box /	Units/Outer Box /	Reel	Inner Box	Outer Box